

 <b>FUZETEC TECHNOLOGY CO., LTD.</b>	<b>NO.</b>	<b>PQ18-01ER</b>		
	<b>Product Specification and Approval Sheet</b>	<b>Version</b>	<b>9</b>	<b>Page</b>

## Surface Mountable PTC Resettable Fuse: FSMD1206 Series

### 1. Summary

- (a) **RoHS Compliant & Halogen Free**
- (b) **Applications: All high-density boards**
- (c) **Product Features: Small surface mountable, Solid state, Faster time to trip than standard SMD devices, Lower resistance than standard SMD devices**
- (d) **Operation Current: 0.05A~2.0A**
- (e) **Maximum Voltage: 6V<sub>DC</sub>~60V<sub>DC</sub>**
- (f) **Temperature Range : -40°C to 85°C**

### 2. Agency Recognition

**UL :** File No. E211981  
**C-UL:** File No. E211981  
**TÜV:** File No. R50090556

### 3. Electrical Characteristics (23°C)

Part Number	Hold Current	Trip Current	Rated Voltage	Max Current	Typical Power	Max Time to Trip		Resistance	
	I <sub>H</sub> , A	I <sub>T</sub> , A	V <sub>MAX</sub> , VDC	I <sub>MAX</sub> , A	P <sub>d</sub> , W	Current	Time	R <sub>MIN</sub>	R <sub>1MAX</sub>
						A	Sec	Ohms	Ohms
FSMD005-1206-R	0.05	0.15	60	10	0.4	0.25	1.50	3.600	50.000
FSMD010-1206-R	0.10	0.25	60	10	0.4	0.50	1.00	1.600	15.000
FSMD012-1206-R	0.12	0.39	48	100	0.6	1.00	0.20	1.400	6.500
FSMD016-1206-R	0.16	0.45	48	100	0.6	1.00	0.30	1.100	5.000
FSMD020-1206-R	0.20	0.40	30	100	0.4	8.00	0.10	0.600	2.500
FSMD025-1206-R	0.25	0.50	16	100	0.6	8.00	0.08	0.550	2.300
FSMD025-24-1206-R	0.25	0.50	24	40	0.6	8.0	0.08	0.550	2.300
FSMD035-1206-R	0.35	0.75	16	100	0.4	8.00	0.10	0.300	1.200
FSMD035-30-1206R	0.35	0.75	30	40	0.6	8.00	0.10	0.300	1.200
FSMD050-1206-R	0.50	1.00	8	100	0.4	8.00	0.10	0.150	0.700
FSMD050-24-1206R	0.50	1.00	24	100	0.6	8.00	0.10	0.150	0.750
FSMD075-1206R	0.75	1.50	6	100	0.6	8.00	0.20	0.090	0.290
FSMD075-16-1206R	0.75	1.50	16	100	0.6	8.00	0.20	0.090	0.290
FSMD100-1206R	1.00	1.80	6	100	0.6	8.00	0.30	0.055	0.210
FSMD110-1206R	1.10	2.20	6	100	0.8	8.00	0.30	0.040	0.180
FSMD150-1206R	1.50	3.00	6	100	0.8	8.00	1.00	0.040	0.120
FSMD200-1206R	2.00	3.50	6	100	0.8	8.00	1.50	0.018	0.080

I<sub>H</sub>=Hold current-maximum current at which the device will not trip at 23°C still air.

I<sub>T</sub>=Trip current-minimum current at which the device will always trip at 23°C still air.

V<sub>MAX</sub>=Maximum voltage device can withstand without damage at it rated current.(I<sub>MAX</sub>)

I<sub>MAX</sub>= Maximum fault current device can withstand without damage at rated voltage (V<sub>MAX</sub>).

P<sub>d</sub>=Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.

R<sub>MIN</sub>=Minimum device resistance at 23°C prior to tripping.

R<sub>1MAX</sub>=Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.

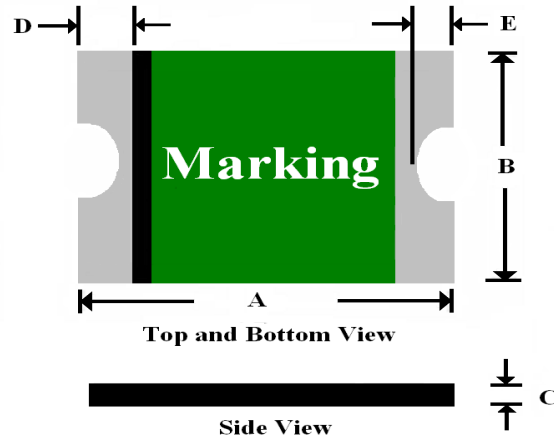
Termination pad characteristics

Termination pad materials: Pure Tin

**NOTE : Specification subject to change without notice.**



### 4. FSMD Product Dimensions (Millimeters)

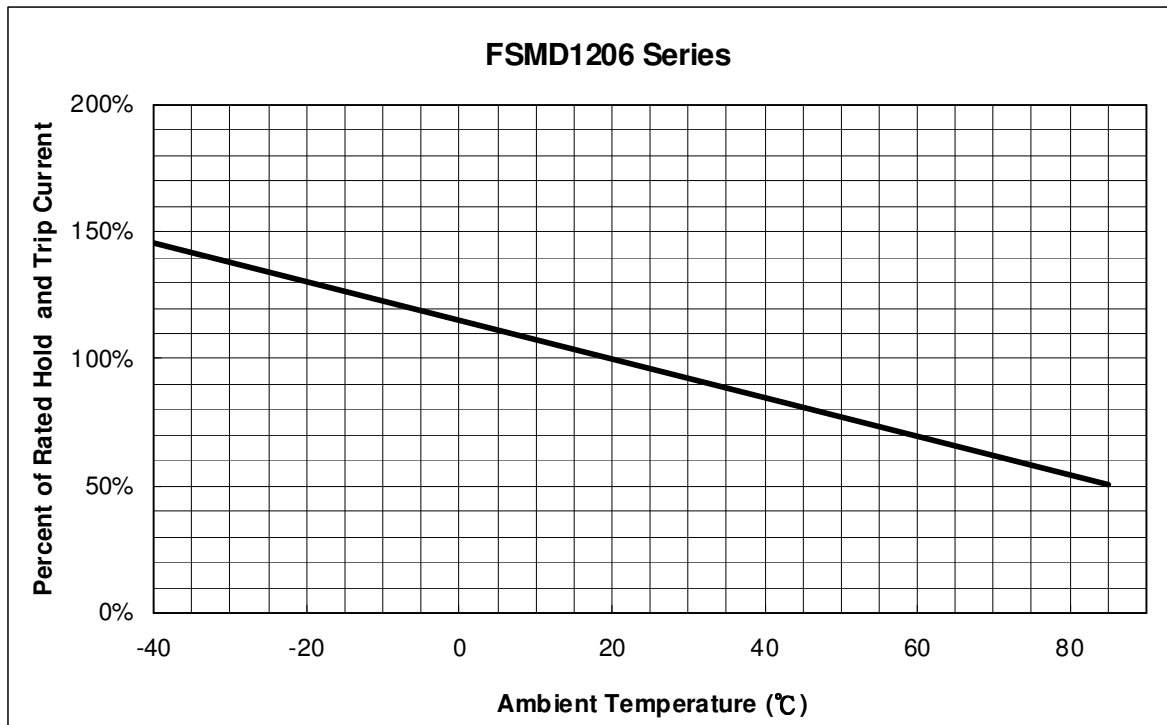


Part Number	A		B		C		D		E	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
FSMD005-1206-R	3.00	3.50	1.50	1.80	0.45	0.85	0.10	0.75	0.10	0.45
FSMD010-1206-R	3.00	3.50	1.50	1.80	0.45	0.85	0.10	0.75	0.10	0.45
FSMD012-1206-R	3.00	3.50	1.50	1.80	0.45	0.85	0.10	0.75	0.10	0.45
FSMD016-1206-R	3.00	3.50	1.50	1.80	0.45	0.75	0.10	0.75	0.10	0.45
FSMD020-1206-R	3.00	3.50	1.50	1.80	0.45	0.75	0.10	0.75	0.10	0.45
FSMD025-1206-R	3.00	3.50	1.50	1.80	0.45	0.75	0.10	0.75	0.10	0.45
FSMD025-24-1206-R	3.00	3.50	1.50	1.80	0.45	0.75	0.10	0.75	0.10	0.45
FSMD035-1206-R	3.00	3.50	1.50	1.80	0.45	0.75	0.10	0.75	0.10	0.45
FSMD035-30-1206R	3.00	3.50	1.50	1.80	0.90	1.30	0.25	0.75	0.10	0.45
FSMD050-1206-R	3.00	3.50	1.50	1.80	0.25	0.55	0.10	0.75	0.10	0.45
FSMD050-24-1206R	3.00	3.50	1.50	1.80	0.90	1.30	0.25	0.75	0.10	0.45
FSMD075-1206R	3.00	3.50	1.50	1.80	0.45	1.25	0.25	0.75	0.10	0.45
FSMD075-16-1206R	3.00	3.50	1.50	1.80	0.45	1.25	0.25	0.75	0.10	0.45
FSMD100-1206R	3.00	3.50	1.50	1.80	0.45	1.00	0.25	0.75	0.10	0.45
FSMD110-1206R	3.00	3.50	1.50	1.80	0.45	1.00	0.25	0.75	0.10	0.45
FSMD150-1206R	3.00	3.50	1.50	1.80	0.80	1.40	0.25	0.75	0.10	0.45
FSMD200-1206R	3.00	3.50	1.50	1.80	0.85	1.60	0.25	0.75	0.10	0.45

NOTE : Specification subject to change without notice.

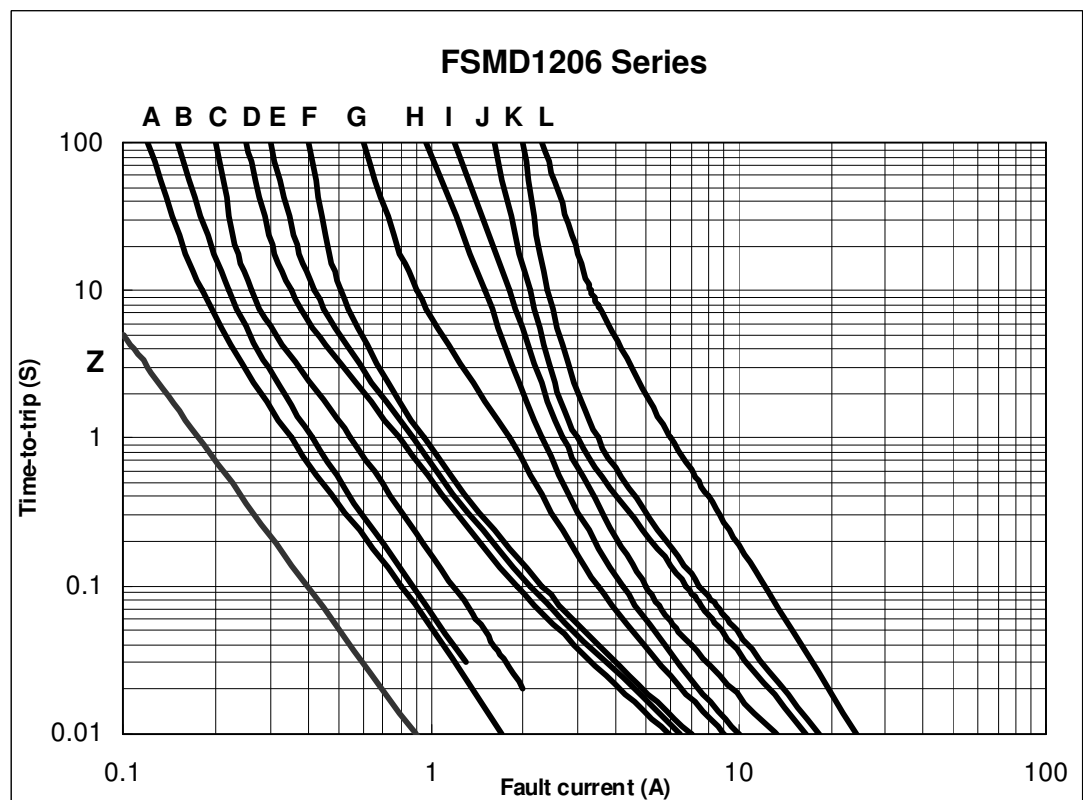


### 5. Thermal Derating Curve



### 6. Typical Time-To-Trip at 23°C

- Z= FSMD005-1206-R
- A= FSMD010-1206-R
- B= FSMD012-1206-R
- C= FSMD016-1206-R
- D= FSMD020-1206-R
- E= FSMD025-1206-R / 025-24-1206-R
- F= FSMD035-1206-R / 035-60-1206R
- G= FSMD050-1206-R / 050-24-1206R
- H= FSMD075-1206R / 075-16-1206R
- I= FSMD100-1206R
- J= FSMD110-1206R
- K= FSMD150-1206R
- L= FSMD200-1206R



NOTE : Specification subject to change without notice.



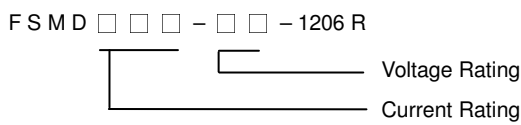
### 7. Material Specification

Terminal pad material: Pure Tin

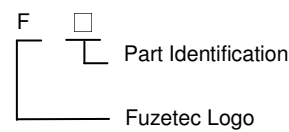
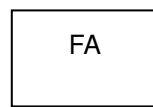
Soldering characteristics: Meets EIA specification RS 186-9E, ANSI/J-std-002 Category 3

### 8. Part Numbering and Marking System

#### Part Numbering System



#### Part Marking System



- FZ = FSMD005-1206-R
- FA = FSMD010-1206-R
- FJ = FSMD012-1206-R
- FK = FSMD016-1206-R
- FB = FSMD020-1206-R
- FL = FSMD025-1206-R
- FP = FSMD025-24-1206-R
- FC = FSMD035-1206-R
- FM = FSMD035-30-1206R
- FD = FSMD050-1206-R
- FN = FSMD050-24-1206R
- FE = FSMD075-1206R
- FO = FSMD075-16-1206R
- FF = FSMD100-1206R
- FG = FSMD110-1206R
- FH = FSMD150-1206R
- FI = FSMD200-1206R

**Warning:** -Operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and/or flame.



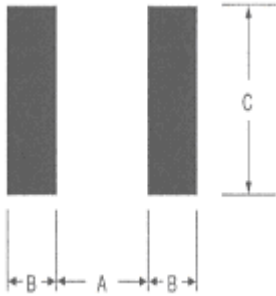
-PPTC device are intended for occasional overcurrent protection. Application for repeated overcurrent condition and/or prolonged trip are not anticipated.

-Avoid contact of PPTC device with chemical solvent. Prolonged contact will damage the device performance.



### 9. Pad Layouts · Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout for each FSMD1206 device



**Pad dimensions (millimeters)**

Device	A Nominal	B Nominal	C Nominal
All 1206 Series	2.00	1.00	1.90

Profile Feature	Pb-Free Assembly
<b>Average Ramp-Up Rate (T<sub>smax</sub> to T<sub>p</sub>)</b>	3 °C/second max.
<b>Preheat :</b>	
Temperature Min (T <sub>smin</sub> )	150 °C
Temperature Max (T <sub>smax</sub> )	200 °C
Time (t <sub>smin</sub> to t <sub>smax</sub> )	60-180 seconds
<b>Time maintained above:</b>	
Temperature(T <sub>L</sub> )	217 °C
Time (t <sub>L</sub> )	60-150 seconds
<b>Peak/Classification Temperature(T<sub>p</sub>) :</b>	260 °C
<b>Time within 5°C of actual Peak :</b>	
Temperature (t <sub>p</sub> )	20-40 seconds
<b>Ramp-Down Rate :</b>	6 °C/second max.
<b>Time 25 °C to Peak Temperature :</b>	8 minutes max.

Note 1: All temperatures refer to of the package,  
measured on the package body surface.

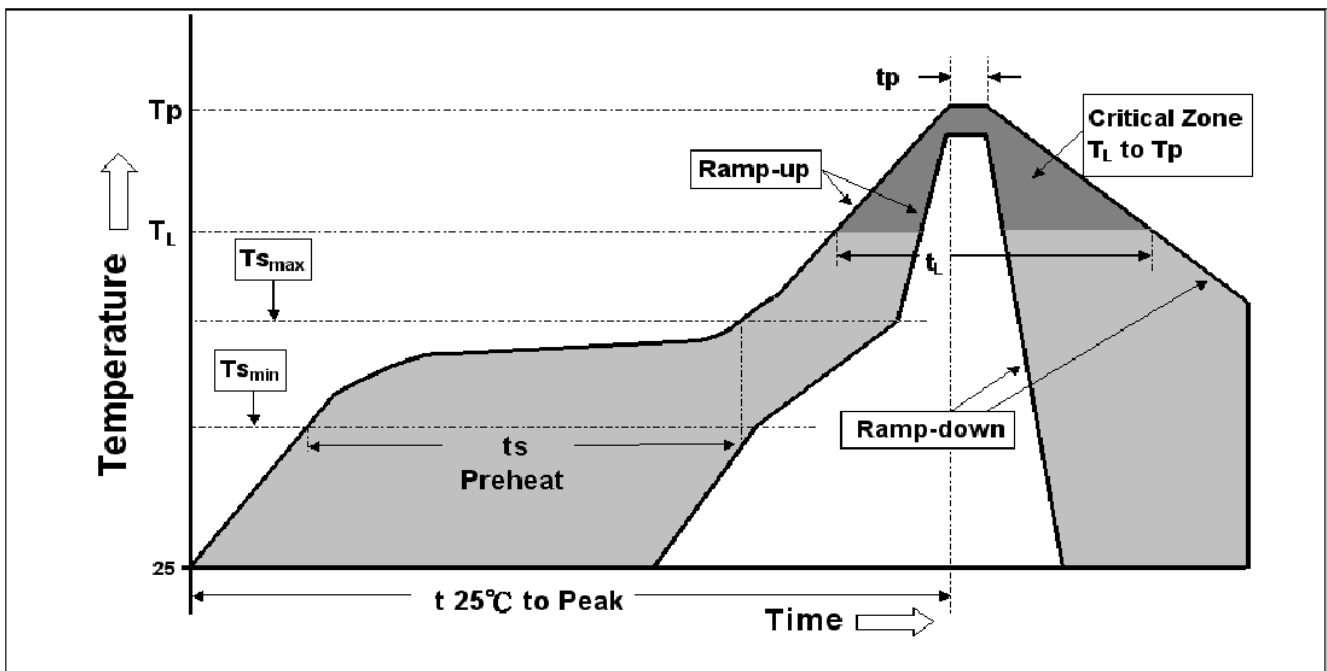
**Solder reflow**

- ※ Due to “Lead Free” nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.
- 1. Recommended max past thickness > 0.25mm.
- 2. Devices can be cleaned using standard methods and aqueous solvent.
- 3. Rework use standard industry practices.
- 4. Storage Environment : < 30°C / 60%RH

**Caution:**

- 1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- 2. Devices are not designed to be wave soldered to the bottom side of the board.

**Reflow Profile**



NOTE : Specification subject to change without notice.